

FG676 - 63/37 (Sn/Pb) SOLDER BALLS
 FGG676 - Sn/Ag/Cu SOLDER BALLS

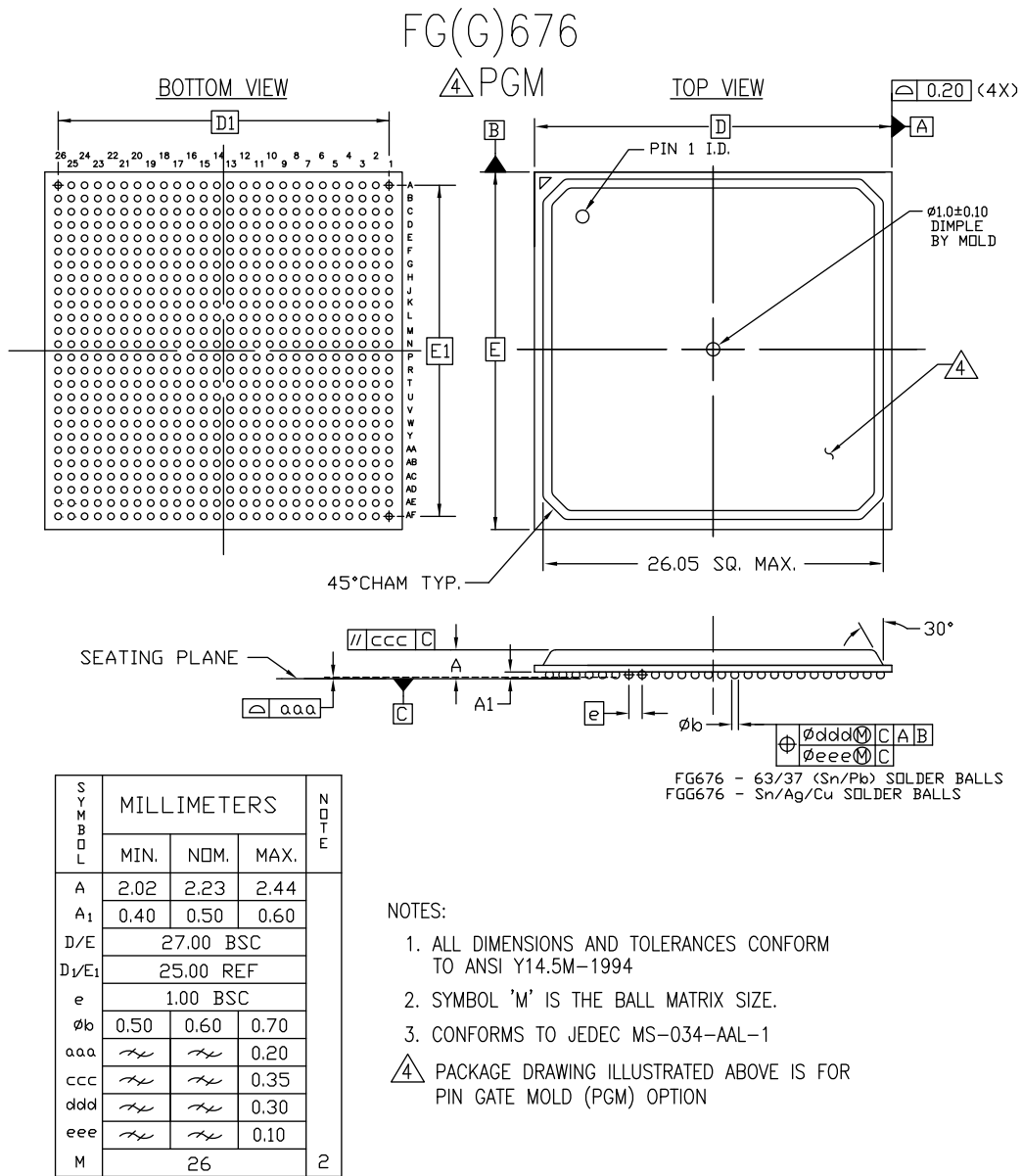
SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.02	2.23	2.44	
A ₁	0.40	0.50	0.60	
D/E	27.00 BSC			
D ₁ /E ₁	25.00 REF			
e	1.00 BSC			
φb	0.50	0.60	0.70	
aaa	<i>xx</i>	<i>xx</i>	0.20	
ccc	<i>xx</i>	<i>xx</i>	0.35	
ddd	<i>xx</i>	<i>xx</i>	0.30	
eee	<i>xx</i>	<i>xx</i>	0.10	
M	26			2

NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
- SYMBOL 'M' IS THE BALL MATRIX SIZE.
- CONFORMS TO JEDEC MS-034-AAL-1
- PACKAGE DRAWING ILLUSTRATED ABOVE IS FOR CORNER GATE MOLD (CGM)
- SEE NEXT PAGE FOR PIN GATE MOLD (PGM) PACKAGE OPTION

pk035_01_032114

Figure 1: Corner Gate Mold Option, FG676/FGG676 Package



pk035_02_032114

Figure 2: Pin Gate Mold Option, FG676/FGG676 Package

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/15/2011	1.3	Revised tolerances for symbol A.
04/04/2014	1.4	Added Figure 2 , pin gate mold package as described in XCN12023 .

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